

news +++ PCIM Asia Shanghai

Shanghai New International Expo Centre, China, 24 – 26 September 2025



PCIM Asia Shanghai Conference 2025 programme to explore power electronics in AI and e-mobility, adds new 'Power Chiplet' session

Shanghai, 7 August 2025. The PCIM Asia Shanghai Conference, Asia's foremost academic gathering for the power electronics industry, returns to Shanghai this September. The 2025 programme will unite industry leaders, technical experts and academics to explore advanced solutions and future trends, highlighting developments in cutting-edge technologies such as silicon carbide (SiC), gallium nitride (GaN), motor drives and motion control, and more. Debuting at the conference is the new “Dialogue with Speakers” zone, where dedicated booths will provide a setting for more direct and in-depth interactions between speakers and attendees.

Held in conjunction with the PCIM Asia Shanghai exhibition, the PCIM Asia Shanghai Conference addresses key industry topics including motion control systems and power supply solutions. The exhibition, in turn, showcases the latest technologies in power electronics components, power conversion, intelligent motion and more. The combined programme brings together leading specialists from the power electronics sector, application fields, and research institutions worldwide to share their knowledge and discuss the future of the industry.

The 2025 conference programme will feature 95 presentations on new applications, advanced technologies and recent developments in the field. Structured around three keynotes, the agenda also incorporates a variety of oral presentations, poster and special sessions.

Keynote presentations

The keynote presentations will cover developments in power electronics, focusing on energy efficiency, power density and reliability across three major application scenarios: data centres, chip power supply and new energy vehicles.

- **Mr Zhaozheng Hou** from Huawei Digital Power will explore the evolution of AI data centre power supply architectures, analysing solutions from high-voltage input to chip-level power delivery chains.
- **Prof Teng Long** from the University of Cambridge will share insights on high-density, high-efficiency power supply technologies for AI computing chips, explaining how advanced power electronics can meet the power demands of high-performance processors.

- **Mr Chang Liu** from Suzhou Inovance Automotive will detail the technological evolution of electric vehicle power electronic converters, covering future developments from system architecture to manufacturing processes.

Special session: “Power Chiplet” Technology, Ultra-high-power Density Platform for Future Power Electronics

This technology spotlight will introduce the concept of the “Power Chiplet”, a new approach for miniaturising components in AI servers and electric vehicle onboard chargers. Organised by Prof Ichiro Omura from Kyushu Institute of Technology and chaired by Mr Naoto Fujishima from Fuji Electric, the programme will bring together leading experts from China, Japan and Europe to discuss methods for maximising power density and system integration using chip-embedded PCB technology. The presentations will explore how this can address challenges related to Moore's Law, reduce costs and enable heterogeneous integration.

- **Prof Ichiro Omura** will share insights on power chiplet technologies for next-generation power electronic systems.
- **Dr Lars Boettcher** from Fraunhofer Institute will present on high-performance power modules integrating silicon carbide MOSFETs.
- **Mr Yoshiaki Aizawa** from Aoi Electronics will discuss chip-embedded panel-level power packaging for AI and automotive applications.
- **Mr Frye Fung** from Zhuhai ACCESS Semiconductor will detail advanced packaging solutions for power chip modules.

Oral and poster session highlights

The conference programme is complemented by a variety of oral presentations and poster exhibits from experts at leading companies and universities, including Fuji Electric, Harbin Institute of Technology, Infineon, Mitsubishi Electric and Tongji University. Drawing from both industrial and academic research, these contributions will address new products and technical applications in areas such as Si devices, e-mobility, power conversion, wide bandgap technologies, packaging, peripheral components and circuitry and smart grids.

New “Dialogue with Speakers” zone to connect innovators with industry leaders

To extend the discussion beyond the formal presentations, the 2025 Conference will introduce a new “Dialogue with Speakers” zone, where dedicated booths will provide a setting for more direct and in-depth interactions between speakers and attendees. Breaking away from the conventional one-way presentation format, these interactive exchanges are designed to facilitate communication across industry, academia, research, and application, enabling attendees to ask further questions, discuss related technical subjects, share their own insights, refine concepts, connect with industry leaders and initiate new business or research collaborations.

Four awards to celebrate outstanding achievements in power electronics

An expanded awards programme will also recognise outstanding contributions to innovation and sustainable development in power electronics. From 95 total submissions, the Conference Advisory Board will select the winners of three established categories: the Best Paper Award, sponsored by Mitsubishi Electric, the Young Engineer Award, sponsored by Semikron Danfoss, and the University Scientist Award, sponsored by Infineon Technologies, evaluating each on its innovation, rigor and application value.

In addition, poster track chairs will select the winner of the new Excellent Poster Award, judging presenters on their paper, poster, presentation, subject matter knowledge and

Q&A performance. Winners will be announced and presented with cash prizes, trophies and certificates at the conference.

Visitor registration for PCIM Asia Shanghai Conference 2025 is now open, with early bird discounts available until 31 August. Register for the conference at:
<https://qr.messefrankfurt.com/03da5>.

To find out more about the speakers, please visit <https://pcimasia-shanghai.cn.messefrankfurt.com/shanghai/zh-cn/programme-events/pcim-asia-conference.html>

To find out more about the event, please visit www.pcimasia-shanghai.com or email pcimasia@china.messefrankfurt.com.

PCIM Asia Shanghai is jointly organised by Guangzhou Guangya Messe Frankfurt Co Ltd and Mesago Messe Frankfurt GmbH. PCIM Asia Shanghai is part of the international PCIM network, other members of the network include:

- PCIM Asia New Delhi Conference: 9 – 10 December 2025, New Delhi, India
- PCIM Expo & Conference: 9 – 11 June 2026, Nuremberg, Germany
- PCIM Asia Shenzhen: 26 – 28 August 2026, Shenzhen, China

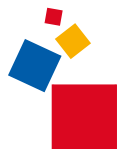
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Your contact:

Ray Sze

Phone: +852 2238 9972

ray.sze@hongkong.messefrankfurt.com

Messe Frankfurt (HK) Ltd
35/F China Resources Building,
26 Harbour Rd,
Wanchai, Hong Kong

www.messefrankfurt.com.hk
www.pcimasia-shanghai.com

Background information on Messe Frankfurt

The Messe Frankfurt Group is the world's largest trade fair, congress and event organiser with its own exhibition grounds. With a workforce of some 2,500 people at its headquarters in Frankfurt am Main and in 28 subsidiaries, it organises events around the world. Group sales in financial year 2024 were around € 775 million. We serve our customers' business interests efficiently within the framework of our Fairs & Events, Locations and Services business fields. One of Messe Frankfurt's key strengths is its powerful and closely knit global sales network, which covers around 180 countries in all regions of the world. Our comprehensive range of services – both onsite and online – ensures that customers worldwide enjoy consistently high quality and flexibility when planning, organising and running their events. We are using our digital expertise to develop new business models. The wide range of services includes renting exhibition grounds, trade fair construction and marketing, personnel and food services.

Sustainability is a central pillar of our corporate strategy. Here, we strike a healthy balance between ecological and economic interests, social responsibility and diversity. For more information, please visit our website at: www.messefrankfurt.com/sustainability

With its headquarters in Frankfurt am Main, the company is owned by the City of Frankfurt (60 percent) and the State of Hesse (40 percent). For more information, please visit our website at: www.messefrankfurt.com